SUMMARY

This summary aims to give you an overview of the information contained in this document. As this is a summary, it does not contain all the information that may be important to you. You should read this document in its entirety before you decide to invest in the [REDACTED].

There are risks associated with any investment. Some of the particular risks in investing in the [REDACTED] are set out in "Risk Factors" in this document. You should read that section carefully before you decide to invest in the [REDACTED].

OVERVIEW

Our Vision

We thrive to be a world-class advanced semiconductor packaging and testing service provider and help advance China's IC industry on the world stage.

Who We Are

We are a semiconductor packaging and testing service provider focusing on advanced packaging and testing solutions for DDICs. Our service portfolio is built around four core process technologies: bumping, chip probing ("**CP**"), chip-on-glass ("**COG**"), and chip-on-film ("**COF**"). Our services are primarily used in DDICs for LCD and AMOLED display panels, with end-use applications spanning consumer electronics, industrial control and automotive electronics. We are also strategically expanding our capabilities into memory IC packaging and testing and are well-positioned to capture opportunities in emerging applications driven by the rapid development of AI.

In 2025, we delivered strong results and achieved significant business growth, with revenue reaching RMB1,783.1 million, representing a year-on-year increase of 18.8%, and EBITDA reaching RMB611.9 million, representing a year-on-year increase of 14.8%. Our shipment volume in 2025 reached 511.3 thousand wafers, making us the fourth-largest DDIC advanced packaging and testing services provider globally. We ranked second in the DDIC advanced packaging and testing market in the Chinese mainland based on revenue in 2025 and ranked second in the packaging and testing market in the Chinese mainland based on 12-inch wafer bumping shipment volume in 2025, according to Frost & Sullivan.

Our key business highlights are illustrated in the following chart:

Scale

Total shipment volume:
511.3 thousand wafers[(1)]
12-inch wafer bumping shipment volume: **416.3** thousand wafers

— **No. 4** globally[(2)]
— **No. 2** in the Chinese mainland[(2)]

Leading Position

In Chinese mainland

No. 2 DDIC advanced packaging and testing service provider[(3)]

No. 8 advanced packaging and testing service provider[(3)]

Among the earliest companies to possess 12-inch wafer bumping capabilities

Growth

23.5%
CAGR of revenue from 2020 to 2025[(4)]

Coverage[(5)]

We serve **four of the global top five** DDIC design companies

We serve **nine of the top ten** DDIC design companies in the Chinese mainland

Technology

Our bump pitch meets the application requirements of **the most advanced products** in the industry[(6)]

The number of bumps that can be formed on a 12-inch wafer reaches **the highest level** in the industry[(7)]

Yield rate of **99.93%+**

Performance

2025 Revenue
RMB1,783.1 million in 2025
18.8% YOY growth

2025 EBITDA
RMB611.9 million
14.8% YOY growth

Notes:

(1) For comparison purposes, for bumping and CP, we divided the shipment volume of 8-inch wafers by 2.25 to convert into an equivalent shipment volume of 12-inch wafers.

(2) Based on (i) total shipment volume of DDIC packaging and testing service providers in 2025 and (ii) 12-inch wafer bumping shipment volume of packaging and testing service providers in 2025, according to Frost & Sullivan.

(3) Ranking of advanced packaging and testing companies is based on their related revenue in 2025, according to Frost & Sullivan.

(4) Source: our annual reports published by the STAR Market of Shanghai Stock Exchange from 2021 to 2025, which were not audited in accordance with IFRS.

(5) Ranking of DDIC design companies is based on their related revenue in 2025, according to Frost & Sullivan.

(6)(7) Our bumping technology is capable of forming tens of millions of bumps on a 12-inch wafer, with a minimum bump width and pitch of 6μm.

Supported by our advanced process technologies, consistent product yields, and strong service capabilities, we have built a broad base of leading customers across the global DDIC design industry. In 2025, we served four of the top five DDIC design companies globally and nine of the top ten in the Chinese mainland. These include some of the world's most prominent DDIC design companies, such as Novatek Microelectronics, Fitipower Integrated Technology, Raydium Semiconductor Corporation, Himax Technologies, Sitronix Technology, Chipone Technology, Ilitek, Viewtrix Technology, New Vision Microelectronics and Solomon Systech. The chips we package and test are used by globally leading display panel manufacturers.

With years of R&D investment and technological development, we have built a strong portfolio of core technologies, including fine pitch bumping technology for DDICs, high-reliability bump structures and processes, high-precision wafer thinning technology, high-stability wafer dicing technology and high-precision and high-stability wafer testing technology. As of the Latest Practicable Date, we held 421 patents, reflecting the depth of our technological capabilities. We continuously refine our production processes and upgrade equipment to drive improvements in precision, yield and reliability, positioning us well to capitalize on the opportunities presented by the localization of the IC supply chain.

Looking ahead, we plan to further expand our advanced packaging and testing capabilities for AMOLED DDICs and large-size display panels, grow our presence in memory ICs and solidify our leading position across our core end-use application areas. We will continue to invest in R&D, broaden the application scope of our services and actively pursue emerging opportunities in automotive electronics and AI-driven applications.

Our Services

We provide advanced semiconductor packaging and testing services primarily for DDICs, which are key components of display panel imaging systems. Our comprehensive service offerings cover the full packaging and testing processes: bumping and chip probing are conducted at the wafer level prior to wafer dicing. The chip is subsequently packaged using either chip-on-glass or chip-on-film, depending on the target display application and module design. Our customers can choose to engage us for one or several of these processes.

- **Bumping:** Bumping is the process of forming bumps on the pads of a wafer through processes such as sputtering, lithography, electrochemical deposition and wet etching. Bumps enable efficient electrical transmission and replace traditional wire bonding in certain advanced packaging applications.

- **CP:** CP is the process of establishing electrical contact with each die on a wafer using a probe card to test its electrical characteristics. Dies that do not meet specified criteria are marked (for example, by ink) and are subsequently screened out at the dicing stage, and therefore do not proceed to downstream packaging and testing processes.

- **COG:** COG is the process of bonding the bumps on a die directly to the electrodes on a glass substrate and encapsulating the connection area with adhesive materials to provide mechanical protection and environmental isolation.
- **COF:** COF is the process of bonding the bumps on a die to the inner leads on a flexible film substrate, providing high-density interconnection and a flexible mounting format for display and related applications.

Through the integration of these processes, we are able to support customers across different process requirements and within the value chain for DDICs.

Our Market Opportunities

Our packaging and testing services support a wide range of end-use application scenarios and are well-positioned in markets with strong growth potential.

- Growing Demand Driven by End-Use Applications
  - o AI-Driven Demand: Advanced Packaging in the AI Era
  - o Large-Size Displays: Bigger Screens, More Advanced Packaging
  - o AMOLED: Structural Upgrade Towards High-End DDICs
  - o Automotive Electronics: Multi-Screen Cabins and Next-Generation Automotive Display
- Outsourcing Tailwind and Industry Specialization
- IC Localization Wave and Policy Support

RESEARCH AND DEVELOPMENT

We consistently invest in research and development to enhance our core process capabilities. Our R&D efforts focus on fine-pitch bumping, wafer thinning and dicing, COF bonding, process automation and the improvement of production consistency and yield. By carrying out technical evaluations, process design, engineering verification and mass-production validation, we continue to adjust and optimize our manufacturing processes in response to customer requirements and changes in product specifications.

We continue to strengthen our R&D capabilities by developing fine-pitch bumping, wafer thinning, photoresist coating, COF bonding and wafer dicing technologies, as well as by enhancing our material applications and production control systems. These efforts have supported measurable improvements in our manufacturing performance and process stability, and have contributed to the expansion of our technical capabilities across DDICs, automotive-grade ICs and advanced packaging applications.

SALES AND MARKETING

Our sales and marketing efforts are centered on building and expanding strategic relationships with our customers, with the goal of becoming and remaining their trusted long-term collaborator. We maintain close collaboration with established DDIC design companies, particularly in Taiwan, while continuing to expand our customer base in the Chinese mainland and engage with overseas customers.

CUSTOMERS AND SUPPLIERS

Our Customers

Our customers primarily consist of DDIC design companies.

In 2023, 2024 and 2025, sales to our five largest customers amounted to RMB899.0 million, RMB996.3 million and RMB1,228.0 million, accounting for 72.6%, 66.4% and 68.9% of our total revenue in the respective years. In 2023, 2024 and 2025, sales to our largest customers amounted to RMB392.9 million, RMB362.8 million and RMB491.2 million, accounting for 31.7%, 24.2% and 27.5% of our total revenue in the respective years. During the Track Record Period, to the best knowledge of our Directors, none of our Directors, their associates or any of our current Shareholders (who, to the knowledge of our Directors, own more than 5% of our share capital) had any interest in our five largest customers in any period during the Track Record Period that are required to be disclosed under the Hong Kong Listing Rules.

See "Business — Sales and Marketing — Our Customers" for further details.

Our Suppliers

Our major suppliers primarily consist of raw materials and equipment. We have established and maintain stable long-term relationships with these major suppliers.

In 2023, 2024 and 2025, purchases from our five largest suppliers amounted to RMB899.2 million, RMB761.1 million and RMB787.8 million, accounting for 58.0%, 61.1% and 62.4% of our total purchases in the respective years. In 2023, 2024 and 2025, purchases from our largest supplier amounted to RMB325.8 million, RMB423.2 million and RMB506.0 million, accounting for 21.0%, 34.0% and 40.1% of our total purchases in the respective years.

See "Business — Supply Chain — Our Suppliers" for further details.

OUR COMPETITIVE STRENGTHS

We believe the following advantages position us well to seize future industry opportunities and achieve sustained growth:

- Leadership Position: First-Mover Edge and Durable Barriers
- Customer Partnerships: Deep Collaboration Built on Technical Excellence
- Full-Process Capabilities: End-to-End Services across High-Value and Fast-Growing Sectors
- R&D Excellence: Deep Process Expertise and Continuous Innovation
- Manufacturing Excellence: Efficient and Reliable Delivery at Scale
- Management and Corporate Culture: A Culture Built on Experience and Execution

OUR GROWTH STRATEGIES

We aim to become a leading advanced semiconductor packaging and testing service provider in China and a world-class player, and to contribute to enhancing the global competitiveness of China's IC industry. To achieve this goal, we plan to implement the following strategies:

- Diversify beyond DDICs and Build New Growth Drivers
- Geographic Expansion: Leverage Our Geographic Edge and Expand Our Customer Base
- R&D and Innovation: Advance Our Technologies to Capture New Opportunities
- Capacity Expansion and Smart Manufacturing: Build for Scale, Deliver with Precision
- Strategic Partnerships and Investments: Expand Our Ecosystem and Cultivate New Growth Areas
- Going Global: Build Our International Presence and Customer Base

COMPETITION

The markets for packaging and testing services industry generally requires continuous investment in technology and manufacturing capabilities, while customer qualification processes and long-term cooperation relationships may further intensify market competition. To maintain and grow our business, we must continue to meet our customers' requirements and deliver differentiated, high-performance services that meet their evolving needs. If we are unable to keep pace with such advancements or fail to differentiate our services in terms of quality or cost, we risk losing market share to our competitors. See "*Industry Overview*" for further details.

SUMMARY OF HISTORICAL FINANCIAL INFORMATION

Summary of Financial Information of Our Group

The following tables sets forth summary financial data from our consolidated financial information during the Track Record Period. The summary financial data set forth below should be read together with, and is qualified in its entirety by reference to, the consolidated financial statements as set out in the Accountants' Report in Appendix I to this document, including the related notes. Our consolidated financial information was prepared in accordance with IFRS Accounting Standards.

Results of Operations

	Year Ended December 31,					
	2023		2024		2025	
	RMB	%	RMB	%	RMB	%
	(in thousands, except for percentages)					
Revenue	1,238,293	100.0	1,501,020	100.0	1,783,135	100.0
Cost of sales	(910,776)	(73.6)	(1,173,871)	(78.2)	(1,395,394)	(78.3)
Gross profit	**327,517**	**26.4**	**327,149**	**21.8**	**387,741**	**21.7**
Other income	32,512	2.6	26,784	1.8	32,488	1.8
Other gains and losses, net	14,753	1.2	16,326	1.1	15,415	0.9
Selling and marketing expenses	(8,410)	(0.7)	(11,465)	(0.8)	(12,348)	(0.7)
Administrative expenses	(74,281)	(6.0)	(75,692)	(5.0)	(82,948)	(4.7)
Research and development expenses	(78,857)	(6.4)	(89,407)	(6.0)	(117,688)	(6.6)
Impairment losses	(16,554)	(1.3)	(17,673)	(1.2)	(26,362)	(1.5)
Finance costs	(1,097)	(0.1)	(22,672)	(1.5)	(37,501)	(2.1)
Share of result of associates, net	—	—	—	—	218	0.0
Profit before income tax	**195,583**	**15.7**	**153,350**	**10.2**	**159,015**	**8.8**
Income tax credit/(expense)	402	0.0	6,414	0.4	(4,284)	(0.2)
Profit for the year	**195,985**	**15.7**	**159,764**	**10.6**	**154,731**	**8.6**

Revenue

During the Track Record Period, we mainly generated revenue from our DDIC advanced packaging and testing services.

By Service Offering

	Year Ended December 31,					
	2023		2024		2025	
	RMB	%	RMB	%	RMB	%
	(in thousands, except for percentages)					
DDIC advanced packaging and testing	**1,168,454**	**94.4**	**1,356,592**	**90.4**	**1,579,071**	**88.6**
Bumping	534,595	43.2	630,545	42.0	748,934	42.0
CP	314,527	25.4	357,931	23.8	390,704	21.9
COG	148,611	12.0	182,796	12.2	185,259	10.4
COF	170,721	13.8	185,320	12.4	254,174	14.3
Others(1)	**69,839**	**5.6**	**144,428**	**9.6**	**204,064**	**11.4**
Total	**1,238,293**	**100.0**	**1,501,020**	**100.0**	**1,783,135**	**100.0**

Note:

(1) Mainly includes sales of recovered gold.

During the Track Record Period, bumping and CP were our principal revenue contributors, and revenue from all of our service offerings recorded growth. Leveraging our established capabilities in bumping and CP, we expect these service offerings to remain our key revenue drivers going forward.

By Geographical Location*

	Year Ended December 31,					
	2023		2024		2025	
	RMB	%	RMB	%	RMB	%
	(in thousands, except for percentages)					
Taiwan	709,309	57.3	800,288	53.3	963,298	54.0
Chinese mainland	504,841	40.8	683,521	45.5	806,262	45.2
Others	24,143	1.9	17,211	1.2	13,575	0.8
Total	**1,238,293**	**100.0**	**1,501,020**	**100.0**	**1,783,135**	**100.0**

Note:

* The geographical location of is determined based on our customers' place of incorporation.

During the Track Record Period, a majority of our revenue was derived from customers incorporated in Taiwan and the Chinese mainland. We expect customers in these two markets to continue to account for a significant portion of our revenue going forward.

Sales Volume and Average Selling Price

	Year Ended December 31,					
	2023		2024		2025	
	Sales volume[1]	Average selling price[2]	Sales volume	Average selling price	Sales volume	Average selling price
	(Piece/ Thousand Die)	(RMB)	(Piece/ Thousand Die)	(RMB)	(Piece/ Thousand Die)	(RMB)
Bumping	475,966.9	1123.2	530,534.7	1188.5	511,312.7	1464.7
CP	451,222.6	697.1	522,331.9	685.3	536,610.6	728.1
COG	1,034,925.5	143.6	1,381,479.1	132.3	1,482,927.6	124.9
COF	326,391.6	523.1	357,513.3	518.4	504,013.8	504.3

Notes:

(1) Sales volume is measured in pieces of 12-inch wafer for bumping and CP, and in thousand dies for COG and COF. For comparison purposes, the number of 8-inch wafers for bumping and CP has been converted into equivalent 12-inch wafer volume by dividing by 2.25.

(2) Average selling price represents revenue generated from the relevant service category divided by the corresponding sales volume, and is presented in RMB/piece for bumping and CP, and RMB/thousand die for COG and COF. For CP, sales volume is presented in piece in accordance with our commercial billing practice, while production capacity is measured in hours due to variations in testing time by chip types.

Gross Profit and Gross Margin

We recorded gross profit as revenue less cost of sales. We recorded gross profit margin as gross profit divided by revenue, expressed as a percentage.

	Year Ended December 31,					
	2023		2024		2025	
	Gross profit	Gross profit margin	Gross profit	Gross profit margin	Gross profit	Gross profit margin
	RMB	%	RMB	%	RMB	%
	(in thousands, except for percentages)					
DDIC advanced packaging and testing	**317,436**	**27.2**	**302,996**	**22.3**	**336,872**	**21.3**
Bumping	125,922	23.6	133,462	21.2	134,334	17.9
CP	106,662	33.9	92,657	25.9	96,189	24.6
COG	29,392	19.8	33,434	18.3	37,219	20.1
COF	55,460	32.5	43,443	23.4	69,130	27.2
Others[1]	**10,081**	**14.4**	**24,153**	**16.7**	**50,869**	**24.9**
Total/Overall[2]	**327,517**	**26.4**	**327,149**	**21.8**	**387,741**	**21.7**

Notes:

(1) Mainly includes sales of recovered gold.

(2) The overall gross profit margin is calculated as gross profit for the year/period divided by revenue for the corresponding period and multiplied by 100%.

Summary of Consolidated Statements of Financial Position

	As of December 31,		
	2023	2024	2025
	(in RMB thousands)		
Non-current assets	2,943,751	2,980,831	3,281,647
Current assets	652,547	1,610,392	1,592,955
Current liabilities	364,886	162,425	296,826
Net current assets	287,661	1,447,967	1,296,129
Total assets less current liabilities	3,231,412	4,428,798	4,577,776
Non-current liabilities	99,381	1,227,727	1,028,781
Net assets	3,132,031	3,201,071	3,548,995
Total equity	3,132,031	3,201,071	3,548,995

Our net current assets decreased from RMB1,448.0 million as of December 31, 2024 to RMB1,296.1 million as of December 31, 2025, primarily due to (i) a decrease in financial assets at FVTPL from RMB681.6 million to RMB534.5 million and (ii) an increase in borrowings from nil to RMB84.6 million, partially offset by (i) an increase in trade and bills receivables from RMB275.3 million to RMB359.0 million and (ii) an increase in other financial assets at amortized cost from nil to RMB60.0 million. Our net current assets increased from RMB287.7 million as of December 31, 2023 to RMB1,448.0 million as of December 31, 2024, primarily due to (i) an increase in financial assets at FVTPL from RMB20.2 million to RMB681.6 million and (ii) an increase in deposits, prepayments and other receivables from RMB43.5 million to RMB76.8 million, partially offset by (i) a decrease in borrowings from RMB185.6 million to nil and (ii) a decrease in other payables and accruals from RMB28.7 million to RMB20.8 million.

Our net assets, being the total equity, increased from RMB2,903.7 million as of January 1, 2023 to RMB3,132.0 million as of December 31, 2023, primarily due to our profit for the year of RMB196.0 million in 2023, partially offset by other comprehensive expense for the year of RMB0.5 million. Our net assets further increased to RMB3,201.1 million as of December 31, 2024, primarily due to our profit for the year of RMB159.8 million in 2024, partially offset by our repurchase of ordinary shares of RMB100.0 million and dividends declared of RMB82.4 million. Our net assets further increased to RMB3,549.0 million as of December 31, 2025, primarily due to our net profit for the year of RMB154.7 million for the year ended December 31, 2025, partially offset by our dividend declared of RMB78.5 million. For further details, see "Consolidated Statements of Changes in Equity" in "Appendix I — Accountants' Report."

Summary of consolidated statements of cash flows

	Year ended December 31,		
	2023	2024	2025
	(in RMB thousands)		
Net cash generated from operating activities	351,460	500,864	692,459
Net cash used in investing activities	(550,083)	(1,248,770)	(642,136)
Net cash generated from/(used in) financing activities	178,996	785,208	(75,796)
Net (decrease)/increase in cash and cash equivalents	**(19,627)**	**37,302**	**(25,473)**
Cash and cash equivalents as of the beginning of year	128,774	109,639	152,038
Cash and cash equivalents as of the end of the year	**109,639**	**152,038**	**129,706**

In 2023, 2024 and 2025, we recorded net cash from operating activities of RMB351.5 million, RMB500.9 million and RMB692.5 million, respectively, primarily due to the profits we generated in each of the respective periods.

See "Financial Information — Liquidity and Capital Resources — Cash Flows."

KEY FINANCIAL RATIOS

	For the year ended/As of December 31,		
	2023	2024	2025
Gross margin[1]	26.4%	21.8%	21.7%
Net profit margin[2]	15.8%	10.6%	8.7%
Return on assets[3]	5.8%	3.9%	3.3%
Return on equity[4]	6.5%	5.0%	4.6%
Current ratio[5]	1.8	9.9	5.4
Quick ratio[6]	1.1	8.1	4.3
Gearing ratio[7]	5.9%	34.8%	28.6%
OCF/net profit ratio[8]	179.3%	313.5%	447.5%

Notes:

(1) Gross margin is calculated as gross profit for the year divided by revenue for the corresponding year and multiplied by 100%.

(2) Net profit margin is calculated as net profit for the year divided by revenue for the corresponding year and multiplied by 100%.

(3) Return on assets is calculated as net profit for the year divided by the average total assets and multiplied by 100%. Average total assets is the sum of the balance of total assets at the beginning and at the end of the year, divided by two.

(4) Return on equity is calculated as net profit for the year divided by the average total equity and multiplied by 100%. Average total equity is the sum of the balance of total equity at the beginning and at the end of the year, divided by two.

(5) Current ratio is calculated as total current assets as at the end of the year divided by total current liabilities as at the end of the corresponding year.

(6) Quick ratio is calculated as total current assets less inventories as at the end of the year and divided by total current liabilities as at the end of the corresponding year.

(7) Gearing ratio is calculated as the total interest bearing liabilities as at the end of the year divided by total equity as at the end of the corresponding year and multiplied by 100%.

(8) OCF/Net profit ratio is calculated as net cash generated from operating activities for the year divided by net profit for the corresponding year and multiplied by 100%.

[REDACTED] EXPENSES

[REDACTED] expenses represent professional fees, [REDACTED] commission and fees incurred in connection with the [REDACTED] and the [REDACTED]. During the Track Record Period, we did not incur any [REDACTED] expenses. Our [REDACTED] expenses are estimated to be approximately HK$[REDACTED] (including [REDACTED] commission), accounting for [REDACTED]% of the gross [REDACTED] of the [REDACTED] (assuming an [REDACTED] of HK$[REDACTED] per H Share, being the low-point of the [REDACTED] range stated in this document, and no exercise of the [REDACTED]). Among our [REDACTED] expenses, approximately HK$[REDACTED] is directly attributable to the issuance of H Shares and will be charged to equity upon completion of the [REDACTED], and approximately HK$[REDACTED] has been or will be charged to our consolidated statements of profit or loss and other comprehensive income. The [REDACTED] expenses we expect to incur would consist of approximately HK$[REDACTED] [REDACTED] related expenses and fees (including [REDACTED] commissions, SFC transaction levy, Stock Exchange trading fee and AFRC transaction levy), approximately HK$[REDACTED] non-[REDACTED]-related expenses and fees of the Sole Sponsor, legal advisors and reporting accountant and approximately HK$[REDACTED] for other non-[REDACTED]-related fees and expenses. The [REDACTED] expenses above are the latest practicable estimate for reference only, and the actual amount may differ from this estimate.

RISK FACTORS

We face risks including those set out in the section headed "Risk Factors." As different investors may have different interpretations and criteria when determining the significance of risks, you should read the "Risk Factors" section in its entirety before you decide to invest in our H Shares. Some of the major risks that we face include:

- Given the complex nature of the packaging and testing process, our yields and customer relationships could suffer from defects in the services we provide or if we do not respond to rapid technological changes.
- We may be unable to obtain the packaging and testing equipment or facilities necessary for our business operations in a timely manner or at a reasonable cost.
- Any deterioration in the general economic conditions or semiconductor end market or a slowdown in the semiconductor and electronics industries could reduce demand for our services.
- We face intense competition in the global semiconductor packaging and testing industry.
- A reversal or slowdown in the outsourcing trend for IC packaging and testing services could adversely affect our growth prospects and profitability.
- If we fail to properly anticipate or respond to changing market conditions or develop and introduce new or enhanced services on a timely basis, our ability to attract and retain customers could be impaired and our competitive position could be harmed.
- We generate the majority of our revenue from a limited number of key customers.
- We make substantial investments in equipment and facilities and the demand of our customers may not develop as we expect.
- Our business may be impacted by geopolitical uncertainties and other political, social and economic instability that leads to business interruptions.
- Our revenues and profitability may decline if we are unable to obtain adequate supplies of raw materials and energy in a timely manner, or at a reasonable price or effectively pass on the price fluctuation of certain raw materials to customers.

FUTURE PLANS AND USE OF [REDACTED]

Assuming an [REDACTED] of HK$[REDACTED] per H Share (being the low-point of the range of the [REDACTED] stated in this Document), we estimate that we will receive net [REDACTED] of approximately HK$[REDACTED] from the [REDACTED] after deducting the [REDACTED] commissions and other estimated expense paid and payable by us in connection with the [REDACTED] (assuming that the [REDACTED] is not exercised). In line with our strategies, we intend to use our [REDACTED] for the purposes and in the amounts set forth below.

- Approximately [REDACTED]%, or approximately HK$[REDACTED], is expected to be used to expand our automotive-grade IC packaging and testing capacity to increase our market share in response to robust demand from the smart vehicle intelligent cabin and in-vehicle display markets.
- Approximately [REDACTED]%, or approximately HK$[REDACTED], is expected to enhance our R&D capabilities through our process technologies and proprietary R&D platform: HITS. The HITS platform is our advanced packaging technology platform for high-end mobile devices and AI-driven applications. It is designed to leverage an organic interposer-based architecture to enable wafer-level planar integration of multiple chips, including logic SoCs, DRAM, LPDDR and connectivity components such as Wi-Fi within a single package. This provides higher performance, smaller form factor and strengthened thermal efficiency.

- Approximately [REDACTED]%, or approximately HK$[REDACTED], is expected to be used for potential investments and acquisitions. In addition to the organic growth of our core packaging and testing business, we intend to selectively pursue strategic collaborations, investments and acquisition opportunities within the semiconductor assembly and testing industry to enhance our overall competitiveness in high-end advanced packaging and testing services.
- Approximately [REDACTED]%, or approximately HK$[REDACTED], is expected to be used for working capital and general corporate purposes.

See "Future Plans and Use of [REDACTED]."

[REDACTED] STATISTICS

The statistics in the following table are based on the assumptions that (i) the [REDACTED] has been completed and [REDACTED] H Shares are newly issued in the [REDACTED], (ii) the [REDACTED] is not exercised, and (iii) no additional Shares are issued pursuant to the 2023 Restricted Share Incentive Plan:

	Based on an [REDACTED] of HK$[REDACTED] per H Share	**Based on an [REDACTED] of HK$[REDACTED] per H Share**
Market value of the H Shares(1)	HK$[REDACTED]	HK$[REDACTED]
Total market capitalization of the Company(2)	HK$[REDACTED]	HK$[REDACTED]
Unaudited [REDACTED] adjusted net tangible assets per Share(3)(4)	HK$[REDACTED]	HK$[REDACTED]

Notes:

(1) The calculation of market value of the H shares is based on [REDACTED] H Shares expected to be issued immediately following the completion of the [REDACTED] (assuming the [REDACTED] is not exercised).

(2) The calculation of market capitalization of the Company is based on the 990,938,171 A Shares in issue as of the Latest Practicable Date and [REDACTED] H Shares expected to be issued immediately following the completion of the [REDACTED] (assuming the [REDACTED] is not exercised). The calculation of market value of the A shares is based on the average closing price of the A Shares of RMB20.14 per A Share for the five business days immediately preceding the Latest Practicable Date.

(3) The unaudited [REDACTED] adjusted net tangible assets per Share is arrived at after adjustments referred to in "Appendix II — Unaudited [REDACTED] Financial Information" in this document.

(4) No adjustment has been made to reflect any trading results or other transactions of us entered into subsequent to December 31, 2025.

DIVIDEND POLICY

In 2023, 2024 and 2025, our Company declared dividends of nil, RMB82.4 million and RMB78.5 million, all of which had been paid in full. See Note 11 to the Accountants' Report included in Appendix I to this document for details.

Pursuant to our Articles of Association, our Board may declare dividends in the future after taking into account our results of operations, financial condition, cash requirements and availability and other factors as it may deem relevant at such time. Any declaration and payment as well as the amount of dividends will be subject to the dividend policy under our constitutional documents, applicable PRC Law and approval by the meeting of our Shareholders. Our Company may distribute dividends in cash, stocks or a combination of cash and stocks, and give priority to profit distribution in cash, where eligible. Pursuant to the dividend policy under our Articles of Association, the aggregate amount of cash dividends distributed by the Company over any consecutive three-year period shall be no less than 30% of our Company's average annual net profit realized over such three-year period. We do not have a fixed dividend distribution ratio.

LISTING ON THE STAR MARKET

Since August 2022, the A Shares of the Company have been listed on the STAR Market. The Directors confirm that, since the A-Share Listing and up to the Latest Practicable Date, there had been no instances of material non-compliance of the Company with the applicable rules of the Shanghai Stock Exchange and other applicable PRC securities laws and regulations. To the best knowledge of the Directors, there are no material matters in relation to the compliance record of the Company on the Shanghai Stock Exchange that should be brought to the attention of the Stock Exchange or potential investors of the [REDACTED]. The PRC Legal Advisor is of the view that, since the A-Share Listing and up to the Latest Practicable Date, there had been no instances of material non-compliance of the Company with the applicable rules of the Shanghai Stock Exchange and other applicable PRC securities laws and regulations. Based on the independent due diligence conducted by the Sole Sponsor and the PRC Legal Advisor's view above, no material matter has come to the Sole Sponsor's attention that would reasonably cause them to disagree with the Directors' confirmation with regard to the compliance records of the Company on the Shanghai Stock Exchange.

SINGLE LARGEST GROUP OF SHAREHOLDERS

As of the Latest Practicable Date, the Company was held as to approximately (i) 0.14% directly by Mr. Cheng, (ii) 2.38% directly by Ms. Yang, (iii) 17.57% by Yangzhou Xinruilian, (iv) 3.81% by Converge Achievement, (v) 1.26% by Potential International, and (vi) 1.12% by Hefei Xincheng. Yangzhou Xinruilian was held as to 14% by Ms. Yang as its general partner and 80% by Hefei Bairuifa as a limited partner. Hefei Bairuifa was held as to 0.7% by Ms. Yang as its general partner and 99% by Bai Rui Fa Investment as a limited partner. Bai Rui Fa Investment was controlled by Bai Rui Fa Holding, which was in turn wholly owned by Mega Rich. Mega Rich was wholly owned by Mr. Cheng. Each of Converge Achievement, Potential International and Hefei Xincheng was also controlled by Mr. Cheng. Mr. Cheng and Ms. Yang are spouses. Accordingly, as of the Latest Practicable Date, Mr. Cheng and Ms. Yang, collectively, controlled approximately 26.28% of the total issued share capital of the Company.

Immediately following the completion of the [REDACTED] (assuming the [REDACTED] is not exercised and no additional Shares are issued pursuant to the 2023 Restricted Share Incentive Plan), Mr. Cheng and Ms. Yang, collectively, will control approximately [REDACTED]% of the total issued share capital of the Company. Upon the [REDACTED], Mr. Cheng, Ms. Yang, Yangzhou Xinruilian, Hefei Bairuifa, Bai Rui Fa Investment, Bai Rui Fa Holding, Mega Rich, Converge Achievement, Potential International and Hefei Xincheng will together constitute the Single Largest Group of Shareholders. See "Relationship with Single Largest Group of Shareholders" for details.

RECENT DEVELOPMENTS AND NO MATERIAL ADVERSE CHANGE

Subsequent to the Track Record Period and as of the date of this document, all outstanding convertible bonds of the Company have been fully converted into shares or redeemed in accordance with their respective terms. The Directors confirm that the aforesaid conversion and redemption did not have any material adverse effect on the financial position or results of operations of the Group.

For the three months ended March 31, 2026, we recorded a net loss, primarily due to (i) significant fluctuations in gold prices, the time lag in passing increased costs on to customers and lower capacity utilization as a result of insufficient order volume, which in turn increased unit depreciation and labor costs and led to a decline in gross profit and (ii) increased R&D expenses, share-based compensation expenses and foreign exchange losses as compared with the corresponding period in 2025, which further contributed to the decline in profitability. Since then, gold price fluctuations moderated and our utilization rates also improved. As a result, we do not expect the foregoing to have a material and adverse effect on our business operation and financial condition.

Saved as disclosed above, our Directors confirmed that, as of the date of this document, there has been no material adverse change in our financial position since December 31, 2025 and up to the Latest Practicable Date, and there has been no event since December 31, 2025 that would materially affect the information as set out in "Appendix I — Accountants' Report" to this document.